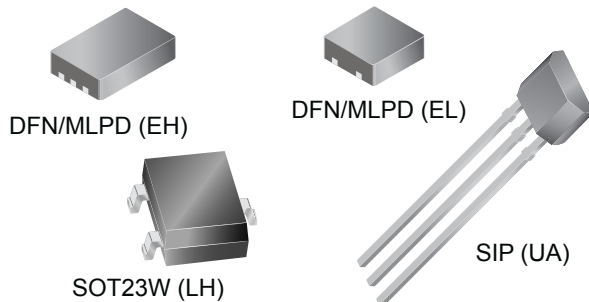


## Micropower, Ultrasensitive Hall-Effect Switches

### Features and Benefits

- Micropower operation
- Operation with north or south pole
- 2.5 to 3.5 V battery operation
- Chopper stabilized
  - Superior temperature stability
  - Extremely low switchpoint drift
  - Insensitive to physical stress
- High ESD protection
- Solid-state reliability
- Small size
- Easily manufacturable with magnet pole independence

### Packages:



Not to scale

### Description

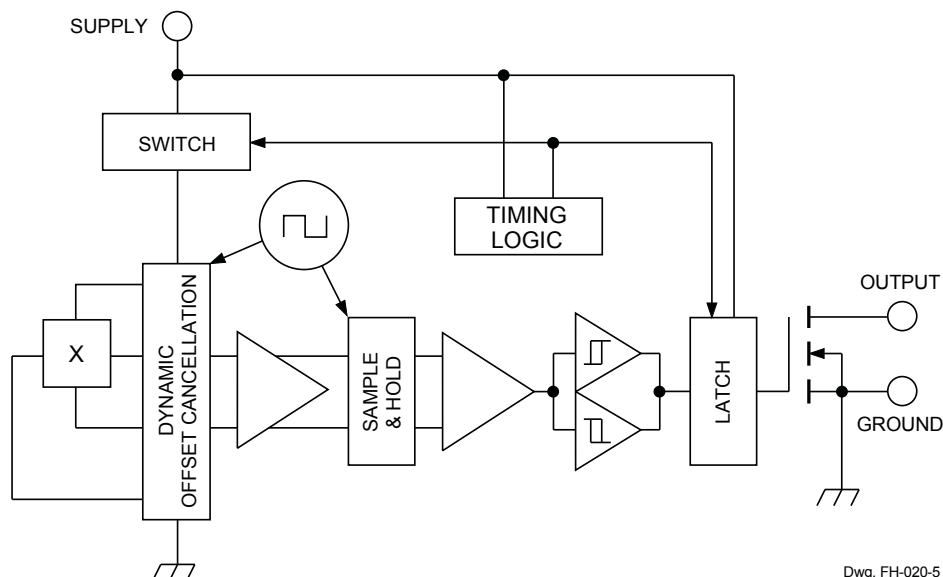
The A 3211 and A3212 integrated circuits are ultrasensitive, pole independent Hall-effect switches with latched digital output. These devices are especially suited for operation in battery-operated, hand-held equipment such as cellular and cordless telephones, pagers, and palmtop computers. A 2.5 to 3.5 V operation and a unique clocking scheme reduce the average operating power requirements to less than 15  $\mu\text{W}$  with a 2.75 V supply.

Unlike other Hall-effect switches, either a north or south pole of sufficient strength will turn the output on in the A3212, and in the absence of a magnetic field, the output is off. The A3211 provides an inverted output. The polarity independence and minimal power requirements allow these devices to easily replace reed switches for superior reliability and ease of manufacturing, while eliminating the requirement for signal conditioning.

Improved stability is made possible through chopper stabilization (dynamic offset cancellation), which reduces the residual offset voltage normally caused by device overmolding, temperature dependencies, and thermal stress.

*Continued on the next page...*

### Functional Block Diagram



## Description (continued)

This device includes on a single silicon chip a Hall-voltage generator, small-signal amplifier, chopper stabilization, a latch, and a MOSFET output. Advanced CMOS processing is used to take advantage of low-voltage and low-power requirements, component matching, very low input-offset errors, and small component geometries.

Four package styles provide magnetically optimized solutions for most applications. Miniature low-profile surface-mount package types *EH* and *EL* (0.75 and 0.50 mm nominal height) are leadless, *LH* is a 3-pin low-profile SMD, and *UA* is a three-pin SIP for through-hole mounting. Packages are lead (Pb) free (suffix, *-T*) with 100% matte tin plated leadframes.

## Selection Guide

| Part Number  | Packing*                | Package                                     | Ambient Temperature<br>T <sub>A</sub> (°C) | State in<br>Magnetic Field |
|--------------|-------------------------|---------------------------------------------|--------------------------------------------|----------------------------|
| A3211EEHLT–T | 3000 pieces per reel    | 2 mm x 3 mm, 0.75 mm nominal height MLP/DFN | –40 to 85                                  | Off                        |
| A3211EELLT–T | 3000 pieces per reel    | 2 mm x 2 mm, 0.50 mm nominal height MLP/DFN |                                            |                            |
| A3211ELHLT–T | 3000 pieces per reel    | 3-pin surface mount SOT23W                  |                                            |                            |
| A3212EEHLT–T | 3000 pieces per reel    | 2 mm x 3 mm, 0.75 mm nominal height MLP/DFN | –40 to 85                                  | On                         |
| A3212EELLT–T | 3000 pieces per reel    | 2 mm x 2 mm, 0.50 mm nominal height MLP/DFN |                                            |                            |
| A3212ELHLT–T | 3000 pieces per reel    | 3-pin surface mount SOT23W                  |                                            |                            |
| A3212EUA–T   | 500 pieces per bulk bag | SIP-3 through hole                          |                                            |                            |
| A3212LLHLT–T | 3000 pieces per reel    | 3-pin surface mount SOT23W                  | –40 to 150                                 |                            |
| A3212LUA–T   | 500 pieces per bulk bag | SIP-3 through hole                          |                                            |                            |

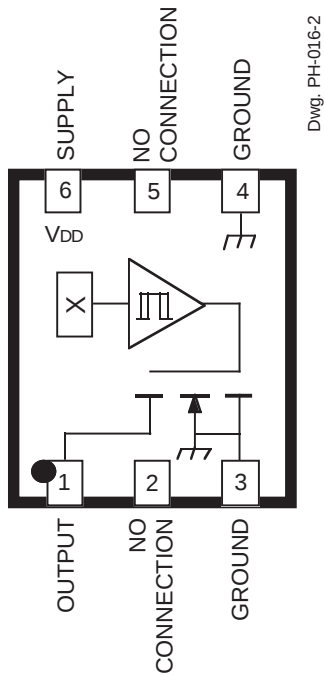
\*Contact Allegro for additional packaging and handling options.



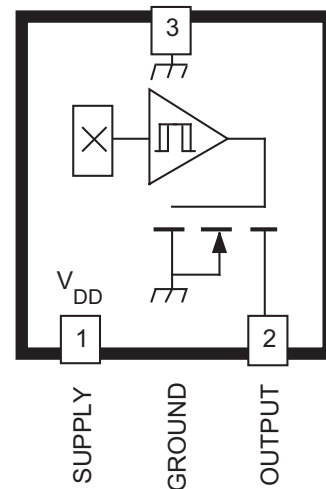
## Absolute Maximum Ratings

| Characteristic                | Symbol     | Notes   | Rating     | Units |
|-------------------------------|------------|---------|------------|-------|
| Supply Voltage                | $V_{DD}$   |         | 5          | V     |
| Magnetic Flux Density         | B          |         | Unlimited  | G     |
| Output Off Voltage            | $V_{OUT}$  |         | 5          | V     |
| Output Current                | $I_{OUT}$  |         | 1          | mA    |
| Operating Ambient Temperature | $T_A$      | Range E | -40 to 85  | °C    |
|                               |            | Range L | -40 to 150 | °C    |
| Maximum Junction Temperature  | $T_J(max)$ |         | 165        | °C    |
| Storage Temperature           | $T_{stg}$  |         | -65 to 170 | °C    |

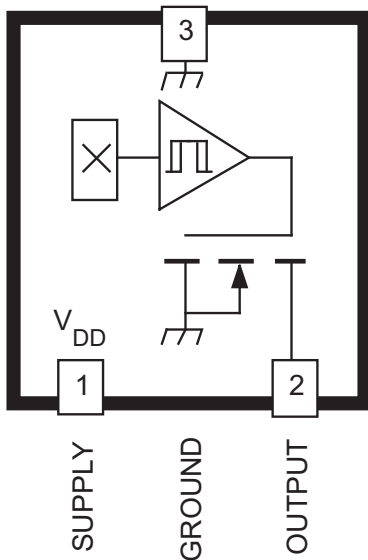
**Package Suffix 'EH' Pinning  
(Leadless Chip Carrier)**



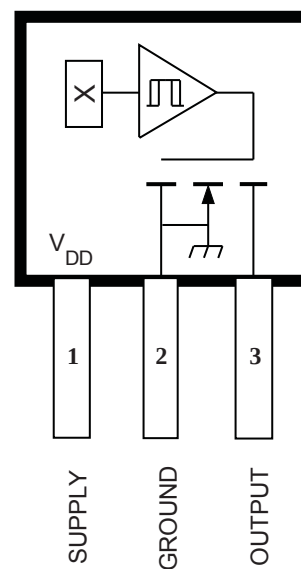
**Package Suffix 'EL' Pinning  
(Leadless Chip Carrier)**



**Package Suffix 'LH' Pinning  
(SOT23W)**



**Package Suffix 'UA' Pinning  
(SIP)**



Pinning is shown viewed from branded side.

**ELECTRICAL CHARACTERISTICS** over operating voltage and temperature range (unless otherwise specified).

| Characteristic         | Symbol        | Test Conditions                     | Limits |       |      |         |
|------------------------|---------------|-------------------------------------|--------|-------|------|---------|
|                        |               |                                     | Min.   | Typ.* | Max. | Units   |
| Supply Voltage Range   | $V_{DD}$      | Operating                           | 2.5    | 2.75  | 3.5  | V       |
| Output Leakage Current | $I_{OFF}$     | $V_{OUT} = 3.5$ V, Output off       | –      | <1.0  | 1.0  | $\mu$ A |
| Output On Voltage      | $V_{OUT}$     | $I_{OUT} = 1$ mA, $V_{DD} = 2.75$ V | –      | 100   | 300  | mV      |
| Awake Time             | $t_{awake}$   |                                     | –      | 45    | 90   | $\mu$ s |
| Period                 | $t_{period}$  |                                     | –      | 45    | 90   | ms      |
| Duty Cycle             | d.c.          |                                     | –      | 0.1   | –    | %       |
| Chopping Frequency     | $f_C$         |                                     | –      | 340   | –    | kHz     |
| Supply Current         | $I_{DD(EN)}$  | Chip awake (enabled)                | –      | –     | 2.0  | mA      |
|                        | $I_{DD(DIS)}$ | Chip asleep (disabled)              | –      | –     | 8.0  | $\mu$ A |
|                        | $I_{DD(AVG)}$ | $V_{DD} = 2.75$ V                   | –      | 5.1   | 10   | $\mu$ A |
|                        |               | $V_{DD} = 3.5$ V                    | –      | 6.7   | 10   | $\mu$ A |

\* Typical data is at  $T_A = 25^\circ\text{C}$  and  $V_{DD} = 2.75$  V, and is for design information only.

**A3211 MAGNETIC CHARACTERISTICS** over operating voltage range (unless otherwise specified)

| Characteristic                                           | Symbol           | Test Conditions                                                                        | Limits |      |      |       |
|----------------------------------------------------------|------------------|----------------------------------------------------------------------------------------|--------|------|------|-------|
|                                                          |                  |                                                                                        | Min.   | Typ. | Max. | Units |
| Over Temperature Range E: T <sub>A</sub> = −40°C to 85°C |                  |                                                                                        |        |      |      |       |
| Operate Points                                           | B <sub>OPS</sub> | South pole to branded side; B > B <sub>OP</sub> , V <sub>OUT</sub> = High (Output Off) | –      | 37   | 55   | G     |
|                                                          | B <sub>OPN</sub> | North pole to branded side; B > B <sub>OP</sub> , V <sub>OUT</sub> = High (Output Off) | −55    | −40  | –    | G     |
| Release Points                                           | B <sub>RPS</sub> | South pole to branded side; B < B <sub>RP</sub> , V <sub>OUT</sub> = Low (Output On)   | 10     | 31   | –    | G     |
|                                                          | B <sub>RPN</sub> | North pole to branded side; B < B <sub>RP</sub> , V <sub>OUT</sub> = Low (Output On)   | –      | −34  | −10  | G     |
| Hysteresis                                               | B <sub>HYS</sub> | B <sub>OPx</sub> - B <sub>RPx</sub>                                                    | –      | 5.9  | –    | G     |

NOTES: 1. Negative flux densities are defined as less than zero (algebraic convention), i.e., –50 G is less than +10 G.

2.  $B_{OPx}$  = operate point (output turns off);  $B_{RPx}$  = release point (output turns on).

3. Typical Data is at  $T_A = +25^{\circ}\text{C}$  and  $V_{DD} = 2.75\text{ V}$  and is for design information only.

4. 1 gauss (G) is exactly equal to 0.1 millitesla (mT).

**A3212 MAGNETIC CHARACTERISTICS** over operating voltage range (unless otherwise specified)

| Characteristic                                            | Symbol           | Test Conditions                                                                        | Limits |      |      |       |
|-----------------------------------------------------------|------------------|----------------------------------------------------------------------------------------|--------|------|------|-------|
|                                                           |                  |                                                                                        | Min.   | Typ. | Max. | Units |
| Over Temperature Range E: T <sub>A</sub> = –40°C to 85°C  |                  |                                                                                        |        |      |      |       |
| Operate Points                                            | B <sub>OPS</sub> | South pole to branded side; B > B <sub>OP</sub> , V <sub>OUT</sub> = Low (Output On)   | –      | 37   | 55   | G     |
|                                                           | B <sub>OPN</sub> | North pole to branded side; B > B <sub>OP</sub> , V <sub>OUT</sub> = Low (Output On)   | –55    | –40  | –    | G     |
| Release Points                                            | B <sub>RPS</sub> | South pole to branded side; B < B <sub>RP</sub> , V <sub>OUT</sub> = High (Output Off) | 10     | 31   | –    | G     |
|                                                           | B <sub>RPN</sub> | North pole to branded side; B < B <sub>RP</sub> , V <sub>OUT</sub> = High (Output Off) | –      | –34  | –10  | G     |
| Hysteresis                                                | B <sub>HYS</sub> | B <sub>OPx</sub> - B <sub>RPx</sub>                                                    | –      | 5.9  | –    | G     |
| Over Temperature Range L: T <sub>A</sub> = –40°C to 150°C |                  |                                                                                        |        |      |      |       |
| Operate Points                                            | B <sub>OPS</sub> | South pole to branded side; B > B <sub>OP</sub> , V <sub>OUT</sub> = Low (Output On)   | –      | 37   | 65   | G     |
|                                                           | B <sub>OPN</sub> | North pole to branded side; B > B <sub>OP</sub> , V <sub>OUT</sub> = Low (Output On)   | –65    | –40  | –    | G     |
| Release Points                                            | B <sub>RPS</sub> | South pole to branded side; B < B <sub>RP</sub> , V <sub>OUT</sub> = High (Output Off) | 10     | 31   | –    | G     |
|                                                           | B <sub>RPN</sub> | North pole to branded side; B < B <sub>RP</sub> , V <sub>OUT</sub> = High (Output Off) | –      | –34  | –10  | G     |
| Hysteresis                                                | B <sub>HYS</sub> | B <sub>OPx</sub> - B <sub>RPx</sub>                                                    | –      | 5.9  | –    | G     |

NOTES: 1. Negative flux densities are defined as less than zero (algebraic convention), i.e., –50 G is less than +10 G.

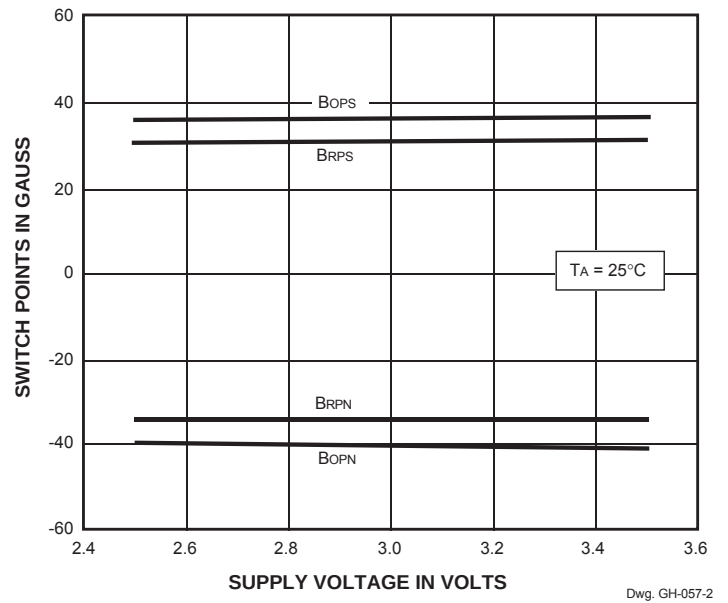
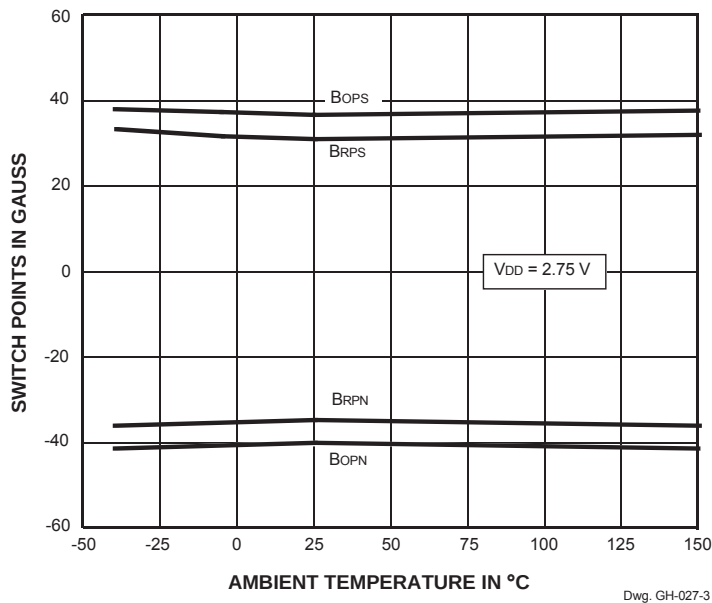
2.  $B_{OPx}$  = operate point (output turns on);  $B_{RPx}$  = release point (output turns off).

3. Typical Data is at  $T_A = +25^{\circ}\text{C}$  and  $V_{DD} = 2.75\text{ V}$  and is for design information only.

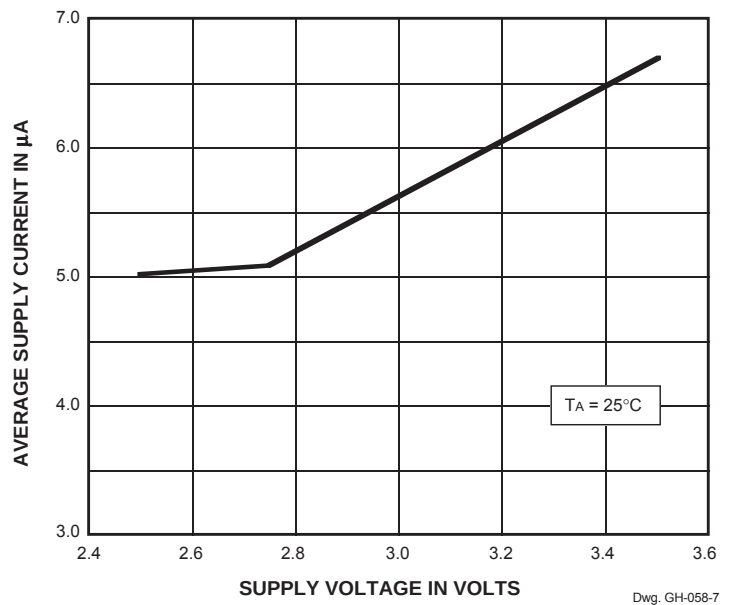
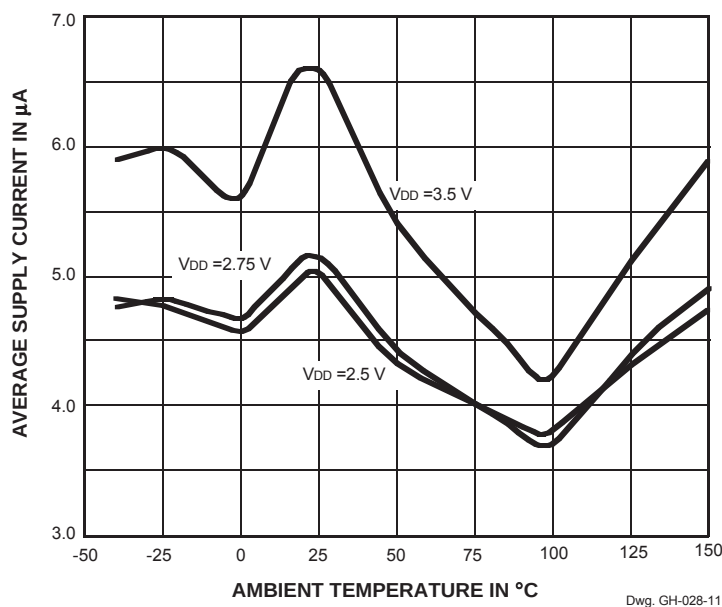
4. 1 gauss (G) is exactly equal to 0.1 millitesla (mT).

**TYPICAL OPERATING CHARACTERISTICS**

**SWITCH POINTS**

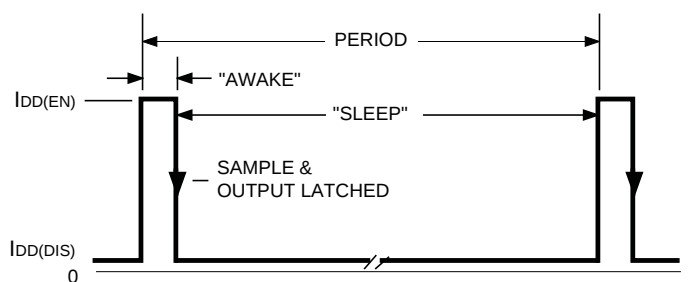


**SUPPLY CURRENT**

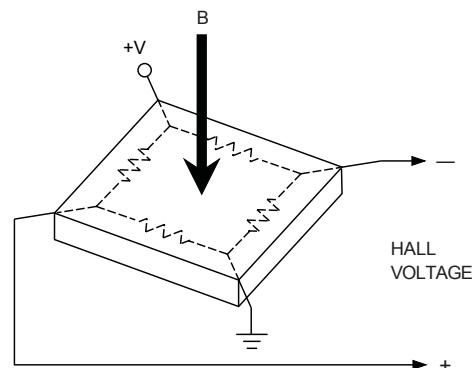


## FUNCTIONAL DESCRIPTION

**Low Average Power.** Internal timing circuitry activates the IC for 45  $\mu$ s and deactivates it for the remainder of the period (45 ms). A short "awake" time allows for stabilization prior to the sampling and data latching on the falling edge of the timing pulse. The output during the "sleep" time is latched in the last sampled state. The supply current is not affected by the output state.



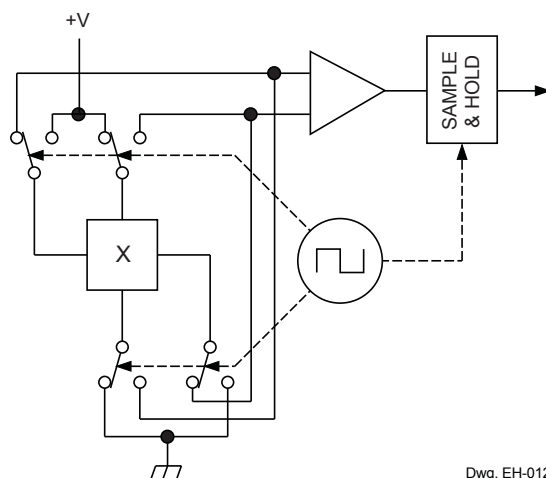
Dwg. WH-017-2



Dwg. AH-011-2

**Chopper-Stabilized Technique.** The Hall element can be considered as a resistor array similar to a Wheatstone bridge. A large portion of the offset is a result of the mismatching of these resistors. These devices use a proprietary dynamic offset cancellation technique, with an internal high-frequency clock to reduce the residual offset voltage of the Hall element that is normally caused by device overmolding, temperature dependencies, and thermal stress. The chopper-stabilizing technique cancels the mismatching of the resistor circuit by changing the direction of the current flowing through the Hall plate using CMOS switches and Hall voltage measurement taps, while maintaining the Hall-voltage signal that is induced by the external magnetic flux. The signal is then captured by a sample-and-hold circuit and further processed using low-offset bipolar circuitry. This technique produces devices that have an extremely stable quiescent Hall output voltage, are immune to thermal stress, and have precise recoverability after temperature cycling. A relatively high sampling frequency is used for faster signal processing capability can be processed.

More detailed descriptions of the circuit operation can be found in: Technical Paper STP 97-10, *Monolithic Magnetic Hall Sensing Using Dynamic Quadrature Offset Cancellation* and Technical Paper STP 99-1, *Chopper-Stabilized Amplifiers With A Track-and-Hold Signal Demodulator*.



Dwg. EH-012-1

## FUNCTIONAL DESCRIPTION (cont'd)

**Operation.** The output of the A3212 switches low (turns on) when a magnetic field perpendicular to the Hall element exceeds the operate point  $B_{OPS}$  (or is less than  $B_{OPN}$ ). After turn-on, the output is capable of sinking up to 1 mA and the output voltage is  $V_{OUT(ON)}$ . When the magnetic field is reduced below the release point  $B_{RPS}$  (or increased above  $B_{RPN}$ ), the device output switches high (turns off). The difference in the magnetic operate and release points is the hysteresis ( $B_{hys}$ ) of the device. This built-in hysteresis allows clean switching of the output even in the presence of external mechanical vibration and electrical noise. The A3211 functions in the same manner, except the output voltage is reversed from the A3212, as shown in the figures to the right.

As used here, negative flux densities are defined as less than zero (algebraic convention), i.e., -50 G is less than +10 G.

**Applications.** Allegro's pole-independent processing technique allows for operation with either a north pole or south pole magnet orientation, enhancing the manufacturability of the device. The state-of-the-art technology provides the same output polarity for either pole face.

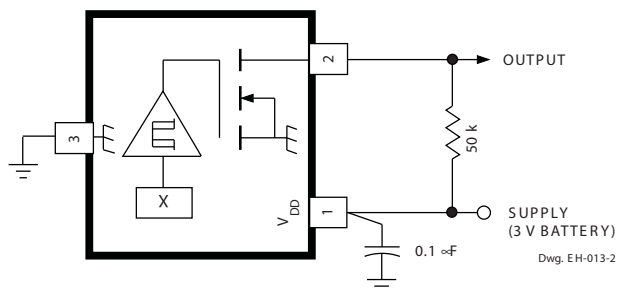
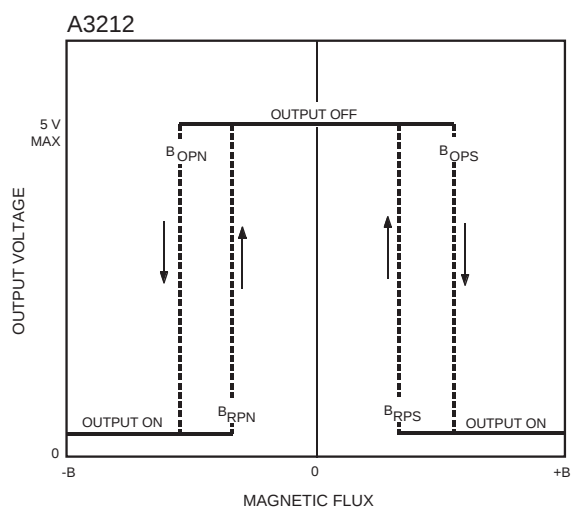
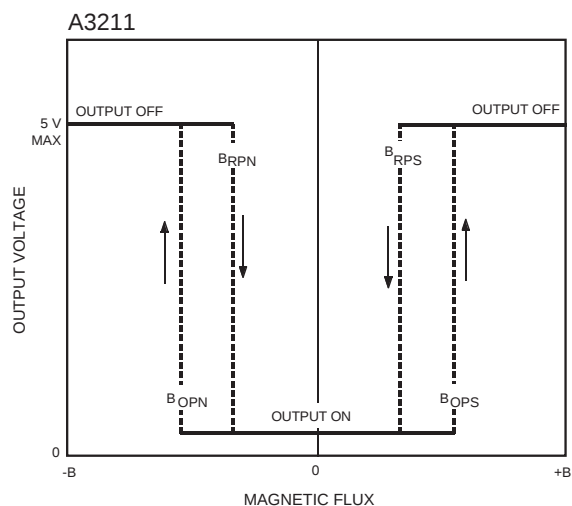
It is strongly recommended that an external bypass capacitor be connected (in close proximity to the Hall element) between the supply and ground of the device to reduce both external noise and noise generated by the chopper-stabilization technique. This is especially true due to the relatively high impedance of battery supplies.

The simplest form of magnet that will operate these devices is a bar magnet with either pole near the branded surface of the device. Many other methods of operation are possible. Extensive applications information for Hall-effect devices is available in:

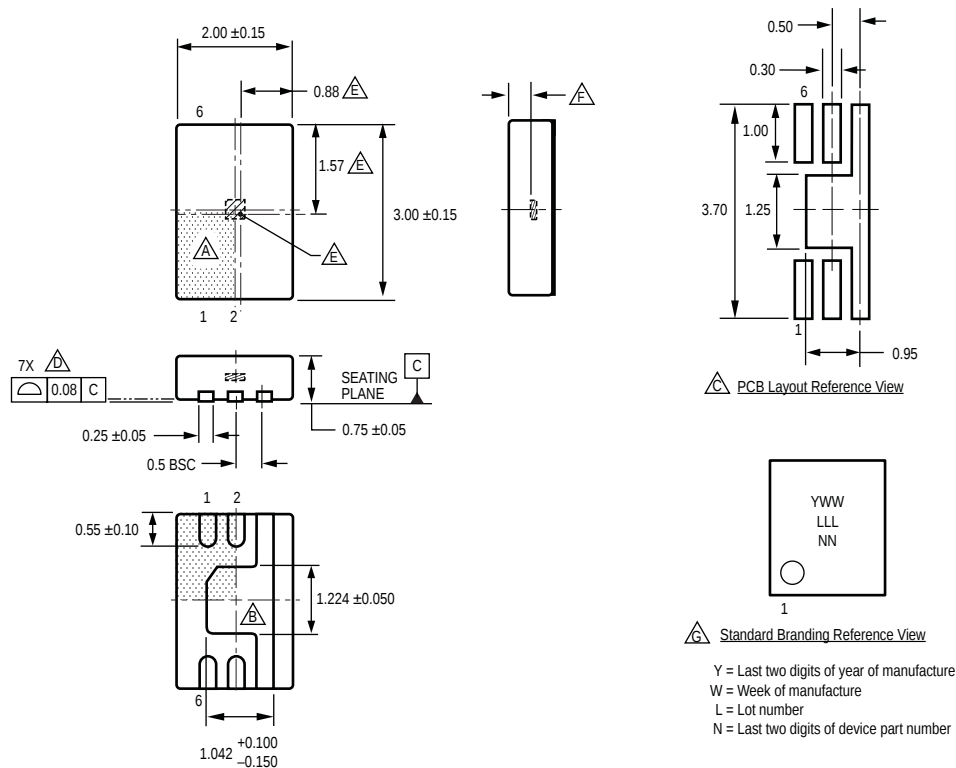
- *Hall-Effect IC Applications Guide*, Application Note 27701;
- *Hall-Effect Devices: Soldering, Gluing, Potting, Encapsulating, and Lead Forming*, Application Note 27703.1;
- *Soldering of Through-Hole Hall-Sensing Devices*, Application Note 27703; and
- *Soldering of Surface-Mount Hall-Sensing Devices*, Application Note 27703.2.

All are provided at

[www.allegromicro.com](http://www.allegromicro.com)



## Package EH, 6-Contact MLP/DFN



For Reference Only, not for tooling use (reference DWG-2861;  
reference JEDEC MO-229WCED, Type 1)  
Dimensions in millimeters  
Exact case and lead configuration at supplier discretion within limits shown

[illegible]

|                                                                                                                                                                                                                                                                                                                                                                                                                                              |                                                                                                                                            |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------|
|  Terminal #1 mark area                                                                                                                                                                                                                                                                                                                                    |  Coplanarity includes exposed thermal pad and terminals |
|  Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion)                                                                                                                                                                                                                                                           |  Hall Element (not to scale)                            |
|  Reference land pattern layout (reference IPC7351); All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5) |  Active Area Depth, 0.18 mm NOM                         |
|                                                                                                                                                                                                                                                                                                                                                                                                                                              |  Branding scale and appearance at supplier discretion   |

The technical drawing illustrates the NNT connector with the following views and dimensions:

- Standard Reference View (Top Left):** Shows the front elevation of the connector. Key dimensions include a total width of  $2.98^{+0.12}_{-0.08}$ , a mounting hole diameter of  $1.47 \triangle$ , a central feature diameter of  $0.84 \triangle$ , a base width of  $0.55 \text{ REF}$ , and a total height of  $2.90^{+0.10}_{-0.20}$ . Features are labeled 1, 2, and 3.
- Standard Reference View (Bottom Left):** Shows the side profile of the connector. Key dimensions include a top width of  $0.95 \text{ BSC}$ , a base width of  $0.40 \pm 0.10$ , a height of  $1.00 \pm 0.13$ , and a top angle of  $8X 10^\circ \text{ REF}$ . The top surface is labeled "Branded Face" and "ZZ2".
- PCB Layout Reference View (Top Right):** Shows the top-down layout of the connector. Key dimensions include a total width of  $0.95$ , a total height of  $2.40$ , and a central feature width of  $0.70$ . A mounting hole diameter of  $1.00$  is indicated.
- Standard Branding Reference View (Bottom Right):** Shows the front elevation of the connector with the "NNT" branding on the top surface. The base width is labeled  $1$ .
- Detail View (Middle):** A cross-sectional view of the connector. Key dimensions include a top width of  $1.91^{+0.19}_{-0.06}$ , a top angle of  $4^\circ \pm 4^\circ$ , a top feature width of  $0.180^{+0.020}_{-0.053}$ , a base width of  $0.25 \text{ BSC}$ , and a base height of  $0.25 \text{ MIN}$ . The top surface is labeled "Seating Plane" and "Gauge Plane".

|          |                                                                                                                                                                               |
|----------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>A</b> | Active Area Depth, 0.28 mm REF                                                                                                                                                |
| <b>B</b> | Reference land pattern layout<br>All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances |
| <b>C</b> | Branding scale and appearance at supplier discretion                                                                                                                          |
| <b>D</b> | Hall element, not to scale                                                                                                                                                    |

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Worcester, Massachusetts 01615-0036 U.S.A.  
1.508.853.5000: [www.allegromicro.com](http://www.allegromicro.com)

Technical drawing of a 3-pin connector, showing front, side, and branding views with dimensions and callouts.

**Dimensions (mm):**

- Top width:  $4.09^{+0.08}_{-0.05}$
- Top chamfer:  $45^\circ$
- Top width (inner):  $1.98$
- Top height:  $1.32$
- Top height (inner):  $1.52 \pm 0.05$
- Top height (inner) chamfer:  $45^\circ$
- Top height (inner) chamfer:  $0.79$  REF
- Top height (inner) chamfer:  $0.41^{+0.03}_{-0.06}$
- Top height (inner) chamfer:  $0.43^{+0.05}_{-0.07}$
- Top height (inner) chamfer:  $1.27$  NOM
- Top height (inner) chamfer:  $15.75 \pm 0.51$
- Top height (inner) chamfer:  $2.16$  MAX
- Top height (inner) chamfer:  $0.51$  REF

**Callouts:**

- A**: Dambar removal protrusion (6X)
- B**: Gate burr area
- C**: Active Area Depth, 0.50 mm REF
- D**: Branding scale and appearance at supplier d
- E**: Hall element, not to scale

**Branding Reference View:**

Standard Branding Reference View

$\mathcal{A}$  = Supplier emblem  
 N = Last two digits of device part number  
 T = Temperature code

For Reference Only; not for tooling use (reference only)  
 Dimensions in millimeters  
 Dimensions exclusive of mold flash, gate burrs, and  
 Exact case and lead configuration at supplier discre

The information included herein is believed to be accurate and reliable. However, Allegro MicroSystems, Inc. assumes no responsibility for its use; nor for any infringement of patents or other rights of third parties which may result from its use.

